







Product Outline:

This is the high efficiency LED with reflector type. EMC 3030 Single color is a surfacemount LED which with heat sink to enhance operating performance. With special binning technology, these LEDs are ideal for architecture lighting and special lighting needs.

Features:

- Green color
- High brightness output @ 150mA,
- High driving current to 200mA.
- Package Dimension = 3.2mmX3.0mmX0.6mm
- RoHS compliant
- Custom Bin available upon special request

Application:

- Warning lamp
- Decoration lamp
- Architecture Lighting
- Garden Lighting
- Horticulture Lighting

Compliance and Certification:



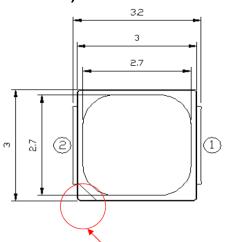


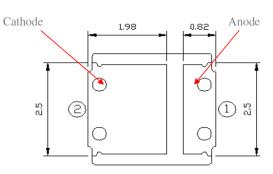


Mechanical Property:



0.6



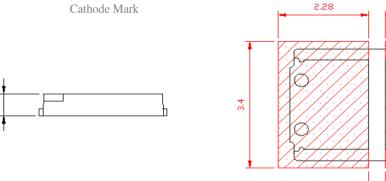


Recommended Solder Pad Design

1.12

0,4

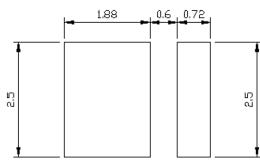
84 4



* All dimensions are in millimeters, * Tolerances are ± 0.10mm.

Tolerances are ± 0.1011111 .

Recommended Solder footprint:



* All dimensions are in millimeters.

- * The LEDs is designed to be reflow soldered on to a PCB. IF dip soldered that QL cannot guarantee its reliability.
- * Reflow soldering must not be performed more than twice.



Characteristics

Absolute	Maximu	m Ratings

Absolute Maximu	(Ta=25℃)		
Parameter	Symbol	Rating	Unit
DC Forward Current	lf	200	mA
Leakage Current	lr	1.0	μA
Power Dissipation	Pd	0.6	W
Pulse Forward Current	lfp	240	mA
LED Junction Temperature	TJ	125	°C
Storage Temperature	Tstg	-40 ~ 100	°C
Operation Temperature	Topr	-40 ~ 85	°C
Soldering Temperature	Tsol	260 < 10 sec	°C
ESD Sensitivity(HBM)		8	KV
Thermal Resistance	Rth	10	°CW

(1) Proper current rating must be observed to maintain junction temperature below maximum at all time(2) IFP Condition: Duty 1/10, Pulse within 10msec

Electrical / Optical Characteristic

(Ta=25 oC)

Product	Color I _F (mA)		V _F (V)		Wavelength		htness n/mW)
			Тур.	max	nm	min	typ.
QLSP04GKH	Green	150	3.0	3.5	515~530	30 lm	40 lm





Groups

Dominant Wavelength

Wd (nm) @ 150mA					
Color Code name Min. Max.					
	DM	515	520		
Green	DN	520	525		
	DP	525	530		

Measurement tolerance is +/- 1nm

Forward Voltage (V_F) Bin:

VF Rank @ 150mA (Vf)						
Color	Code name	Low	High			
	01	2.8	3.0			
Croop	23	3.0	3.2			
Green	45	3.2	3.4			
	67	3.4	3.6			

The forward voltage tolerance is $\pm 0.1V$

Luminous Flux Bin:

Rank @ 150mA (Im)					
Color	Code name	Low	High		
	QK	22.5	25		
Green	QL	25	28		
	QM	28	31.5		

luminous flux tolerance is ± 7%

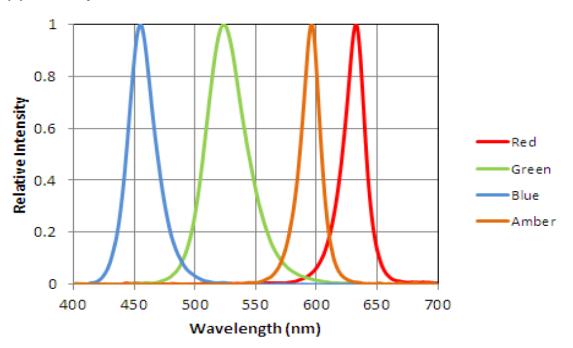




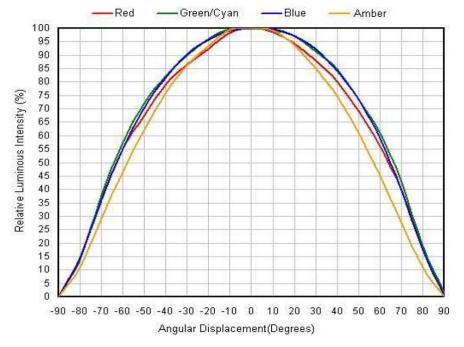
QLSP04GKH V1.0

Characteristic Curves

(1) Color Spectrum



(2). Typical Representative Spatial Radiation Pattern

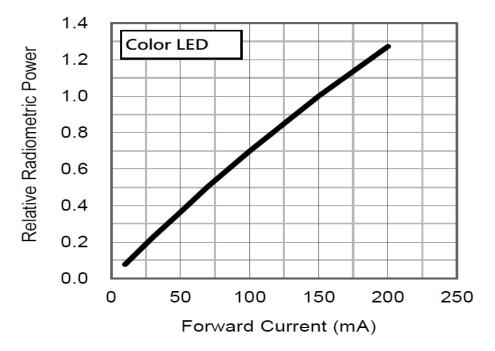




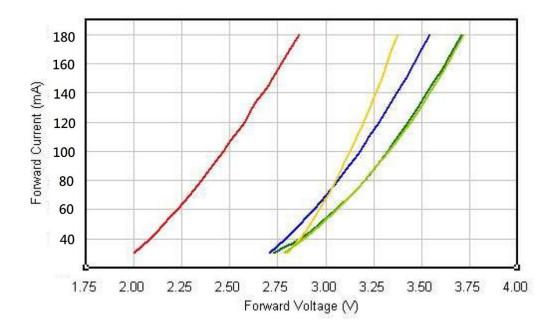




(3). Forward Current Characteristics



(4). Forward Current vs Forward Voltage





Reliability test:

No	Item	Condition	Time/Cycle	Sample size
1	Steady State Operating Life of Room Temperature	25°C Operating	1000 Hrs	20 pcs
2	Steady State Operating Life of Low Temperature -40 $^\circ\!\!\mathbb{C}$	-40°C Operating	1000 Hrs	20 pcs
3	Steady State Operating Life of Low Temperature $60^\circ\!\mathrm{C}$	60℃ Operating	1000 Hrs	20 pcs
4	Steady State Operating Life of Low Temperature $85^\circ\!\!\mathbb{C}$	85°C Operating	1000 Hrs	20 pcs
5	Low temperature storage -40 $^\circ\!\!\!\!\!^\circ$	-40°C Storage	1000 Hrs	20 pcs
6	High temperature storage 100 $^\circ\!\mathrm{C}$	100°C Storage	1000 Hrs	20 pcs
7	Steady State Operating Life of High Humidity Heat $60^\circ\!\!\!\!C90\%$	60°C/90% Operating	1000 Hrs	20 pcs
8	Steady State Pulse Operating Life Condition	25° C 10Hz duty=1/10 Operating	200 Cycle	20 pcs
9	Resistance to soldering heat on PCB (JEDEC MSL3)	pre-store@60℃, 60%RH for 52hrs Tsld max.=260 10sec	3 Times	20 pcs
10	Heat Cycle Test (JEDEC MRC)	25℃~65℃~-10℃, 90%RH, 24hr/1cycle	10 Cycle	20 pcs
11	Thermal shock	-40℃/ 20minr~ 5minr~100℃ /20min	300 Cycle	20 pcs

Judgment Criteria:

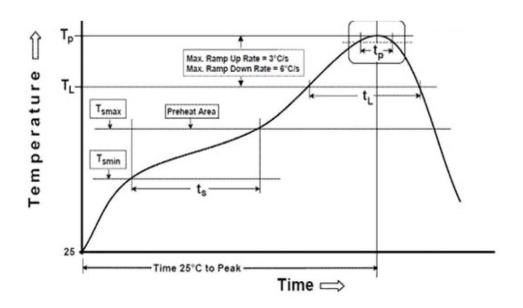
ltem	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	150 mA	∆Vf< 10%
Luminous Flux	lv	150 mA	∆Iv< 30%





Solder Profile:

-The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

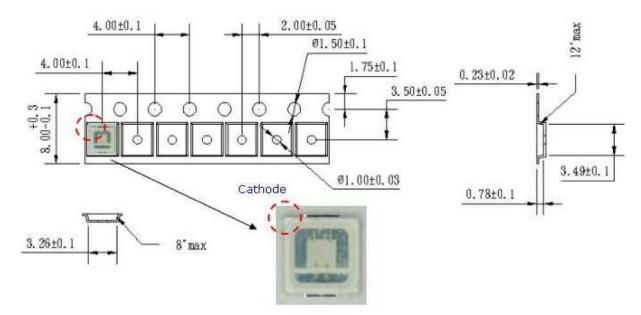


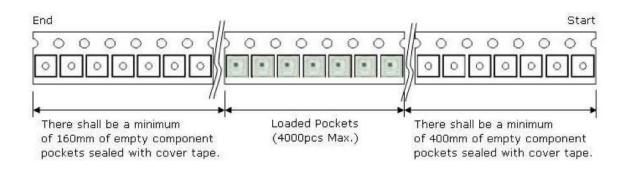
Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Temperature Min(T _{smin})	100°C	150 ℃
Temperature Max(T _{smax})	150 ℃	200 ℃
Time(t _a) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up rate(T_L to T_P)	3℃/second max.	3℃/second max.
Liquidous Temperature(T _L)	183 ℃	217 ℃
Time(t_L) maintained above T_L	60-150 seconds	60-150 seconds
Peak package body temperature(T_P)	235℃	260℃
Time within 5° $_{\mathbb C}$ of Actual Peak	20	20
temperature (t _p)	20seconds*	30 seconds*
Ramp-down rate(T_P to T_L)	6℃/second max.	6℃/second max.
Time 25 $^\circ\!$	6 minutes max.	8 minutes max.

 * Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.



Taping & Packing:

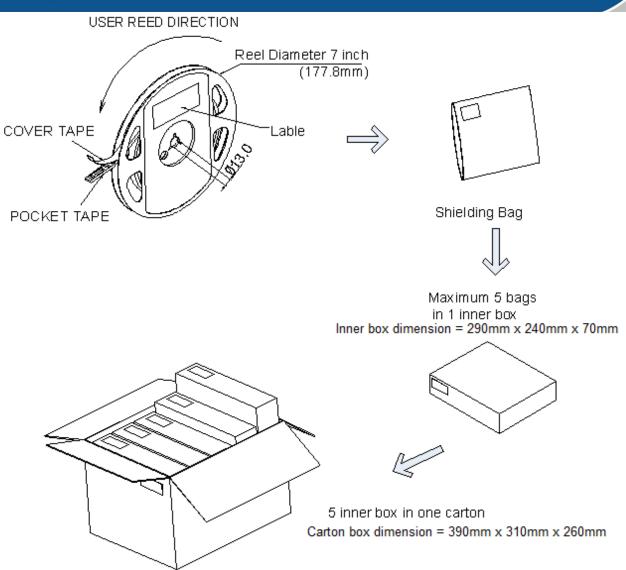




Unit : mm











Labeling

Quantity: XX		QueLighting
	P/N: XXXXXX	

Ordering Information:

Part #	Multiple Quantities	Quantity per Reel
QLSP04GKH		1000, 2000 pcs

Revision History:

Revision Date:	Changes:	Version #:
09-21-2020	Initial release	1.0